



BERGQUIST[®] LIQUI-BOND TLB SA2005RT

TWO-PART, SILICONE THERMAL ADHESIVE

BERGQUIST[®] LIQUI-BOND TLB SA2005RT is a two-part silicone adhesive thermal interface material that delivers high adhesion for a strong structural bond, providing the option to eliminate screws and fasteners while delivering the thermal conductivity of a thermal pad or liquid gap filler. The material's liquid formulation is conducive to automated, high-volume production environments, and its cure adaptability provides excellent process flexibility.

Independent of ambient moisture, *BERGQUIST LIQUI-BOND TLB SA2005RT* reliably cures at multiple temperatures – from room temperature up to 180°C. The cure rate is accelerated at elevated temperatures, achieving maximum shear strength in as fast as 60 seconds.



SHEAR STRENGTH (MPa)	CURE SCHEDULE		
	25°C	50°C	85°C
0.3 (Self-Fixture)	6 hr.	30 min.	5 min.
0.7	1 day	6 hr.	10 min.
1.2	3 days	1 day	1 hr.
1.4	7 days	1 day	1 hr.

PRODUCT PROPERTIES	
Viscosity at 3,000 s ⁻¹ (cP)	70,000
Thermal Conductivity (W/m•K)	2.0
Shore A Hardness	65
Volume Resistivity (Ω•m)	1×10 ¹¹
Flammability Rating	UL 94 V-0

**Across the Board,
Around the Globe.** 
henkel-adhesives.com/thermal

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